

FIG. 1

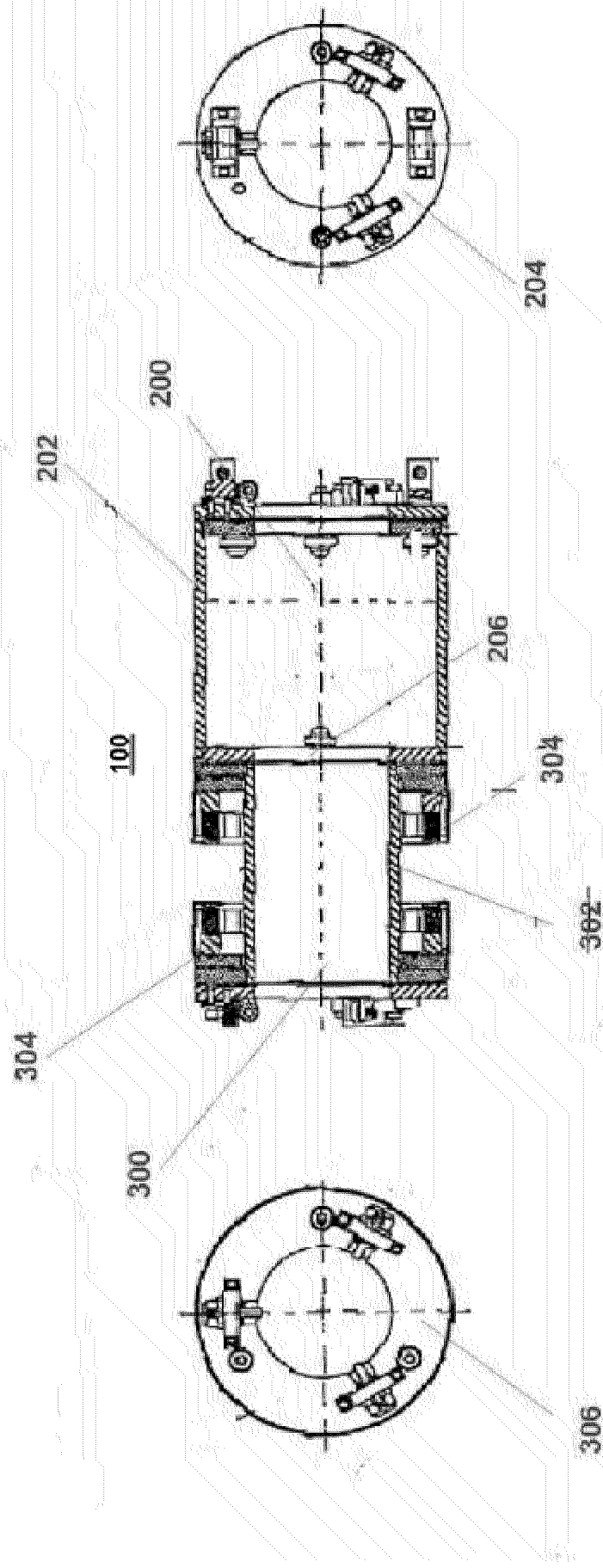


FIG. 2A

FIG. 2B

FIG. 2C

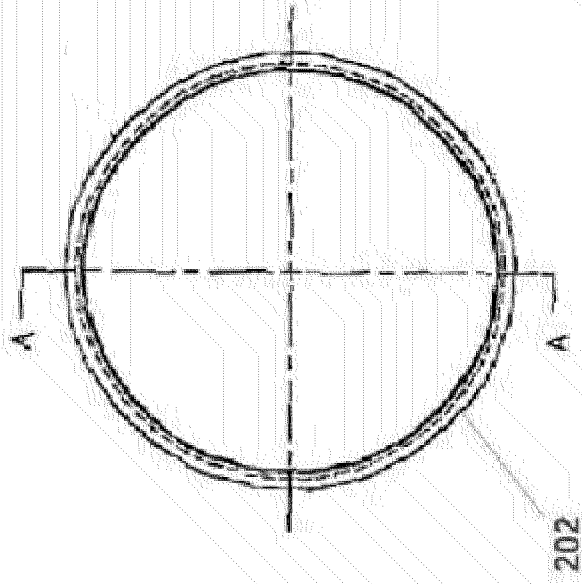
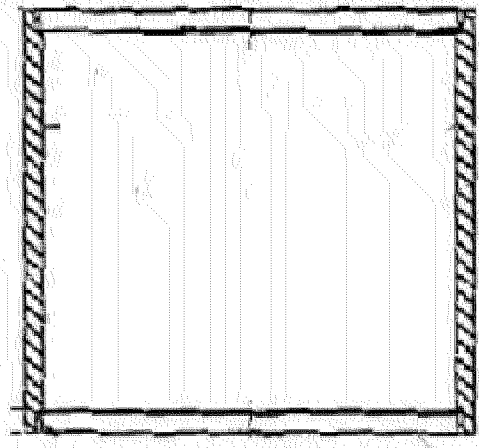


FIG. 3A



SECTION A-A

FIG. 3B

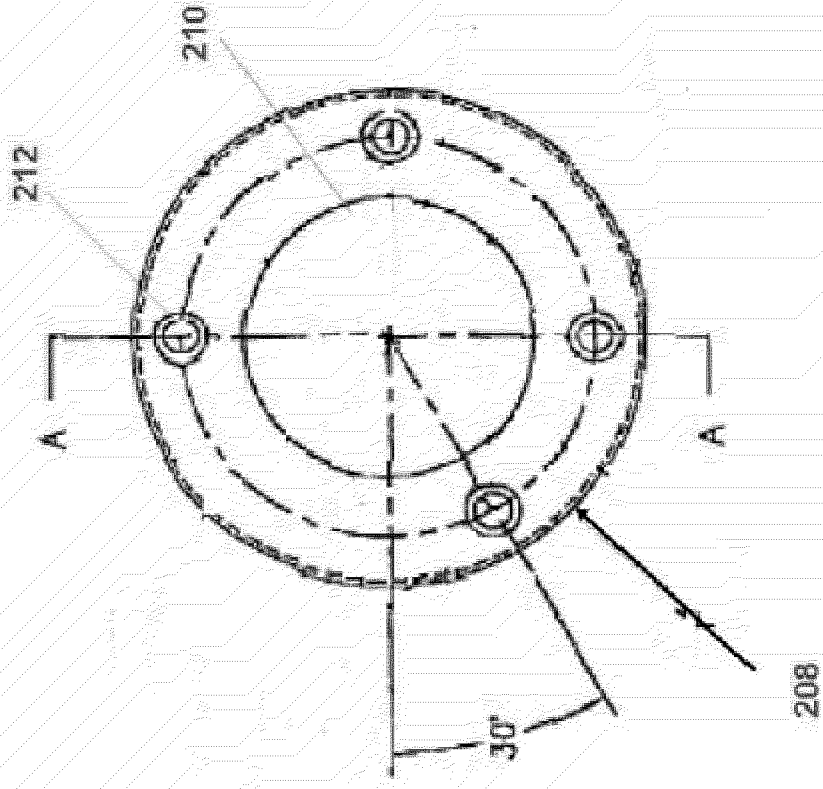


FIG. 4A

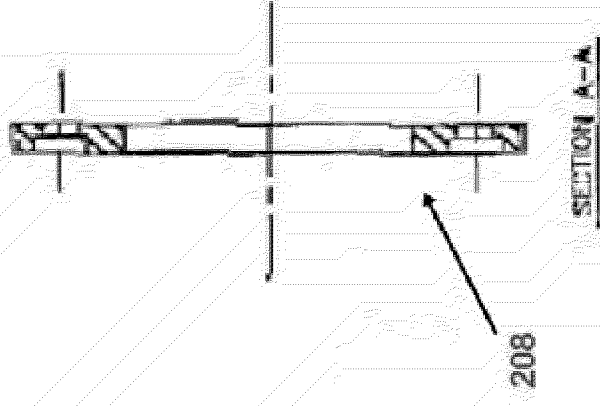


FIG. 4B

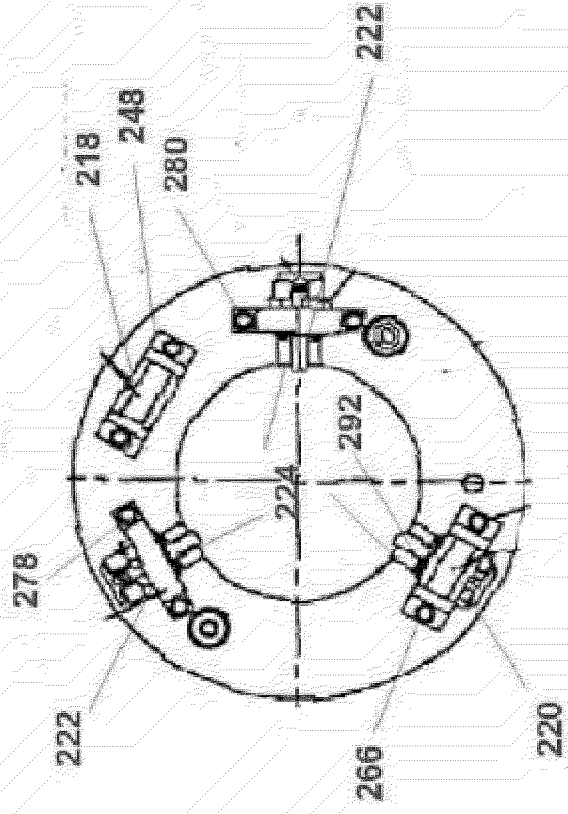


FIG. 5A

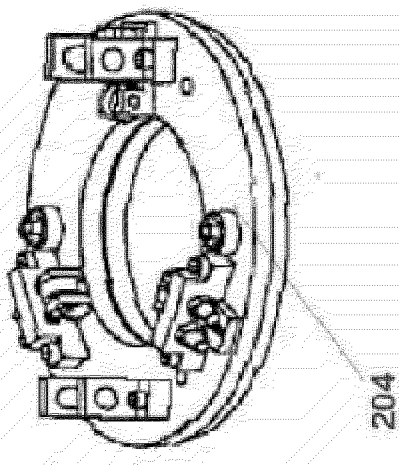


FIG. 5C

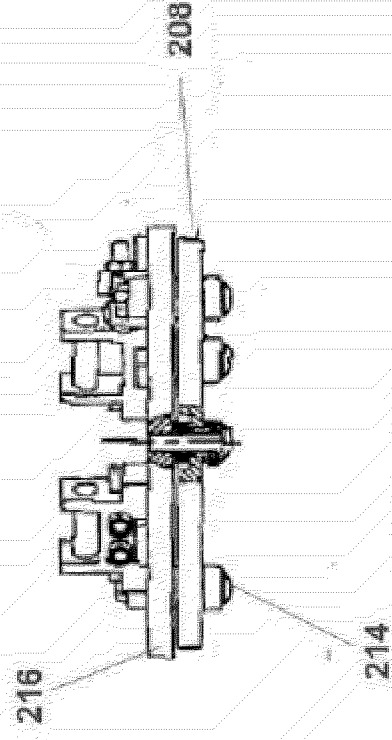


FIG. 5B

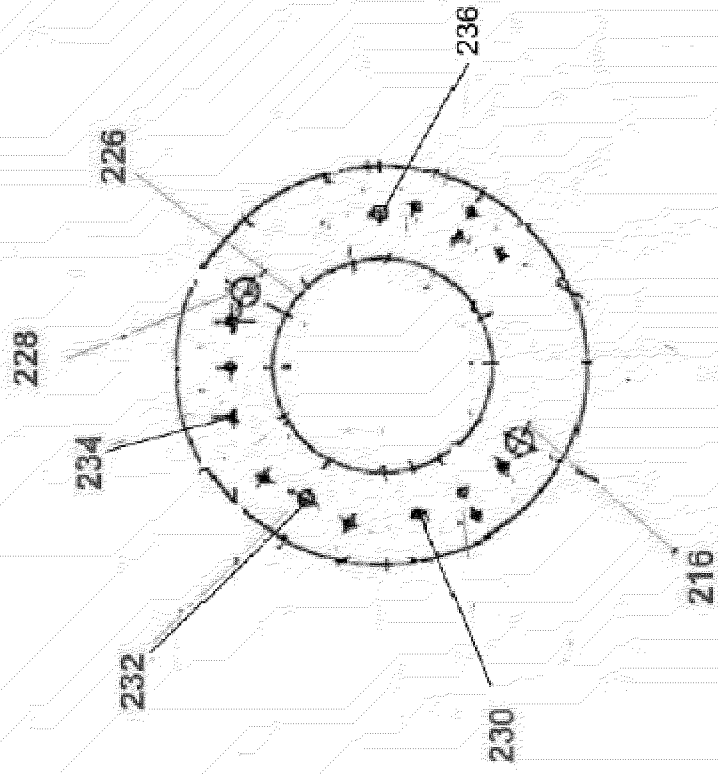


FIG. 6A

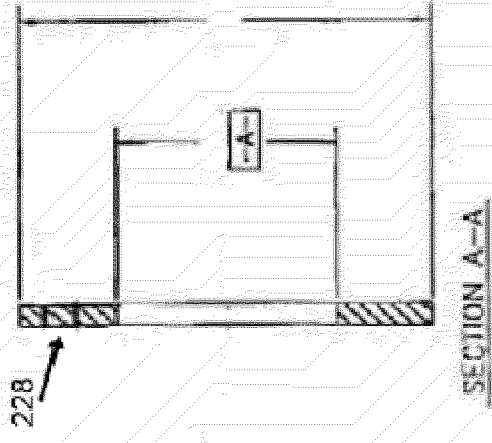


FIG. 6B

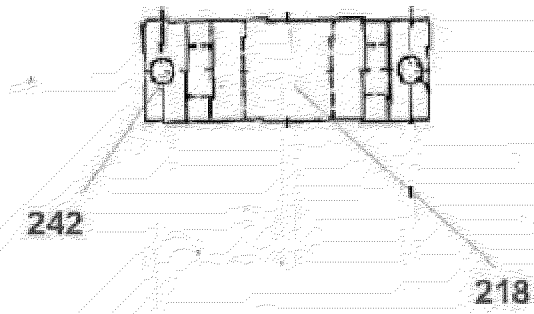


FIG. 7A

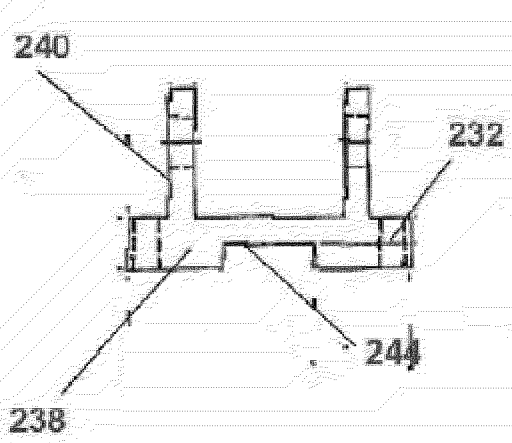


FIG. 7B

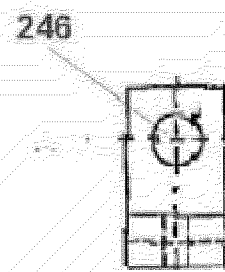


FIG. 7C

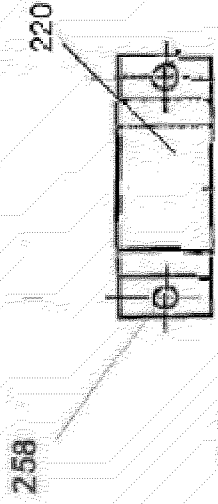


FIG. 8A

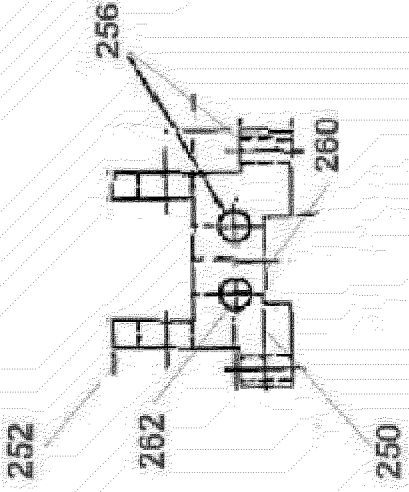


FIG. 8B

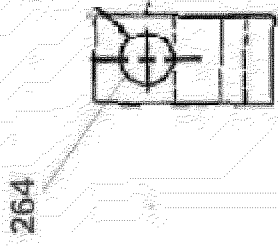


FIG. 8C

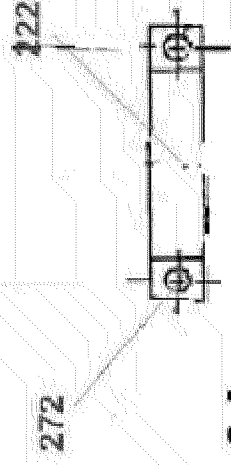


FIG. 9A

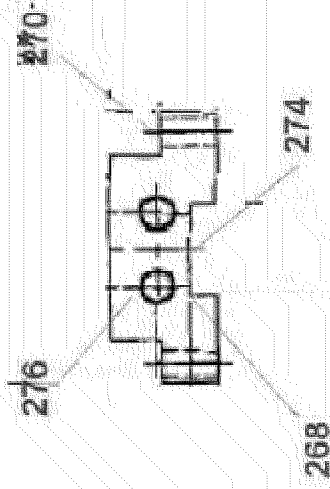


FIG. 9B



FIG. 9C

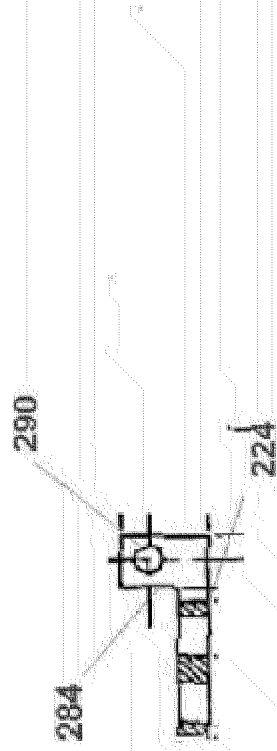


FIG. 10A

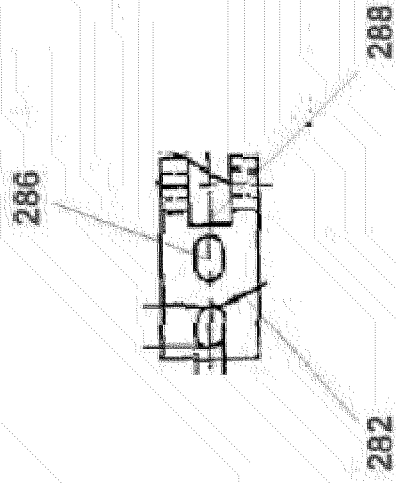
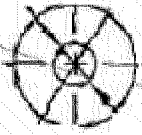


FIG. 10B

294



292

FIG. 11A

292



FIG. 11B

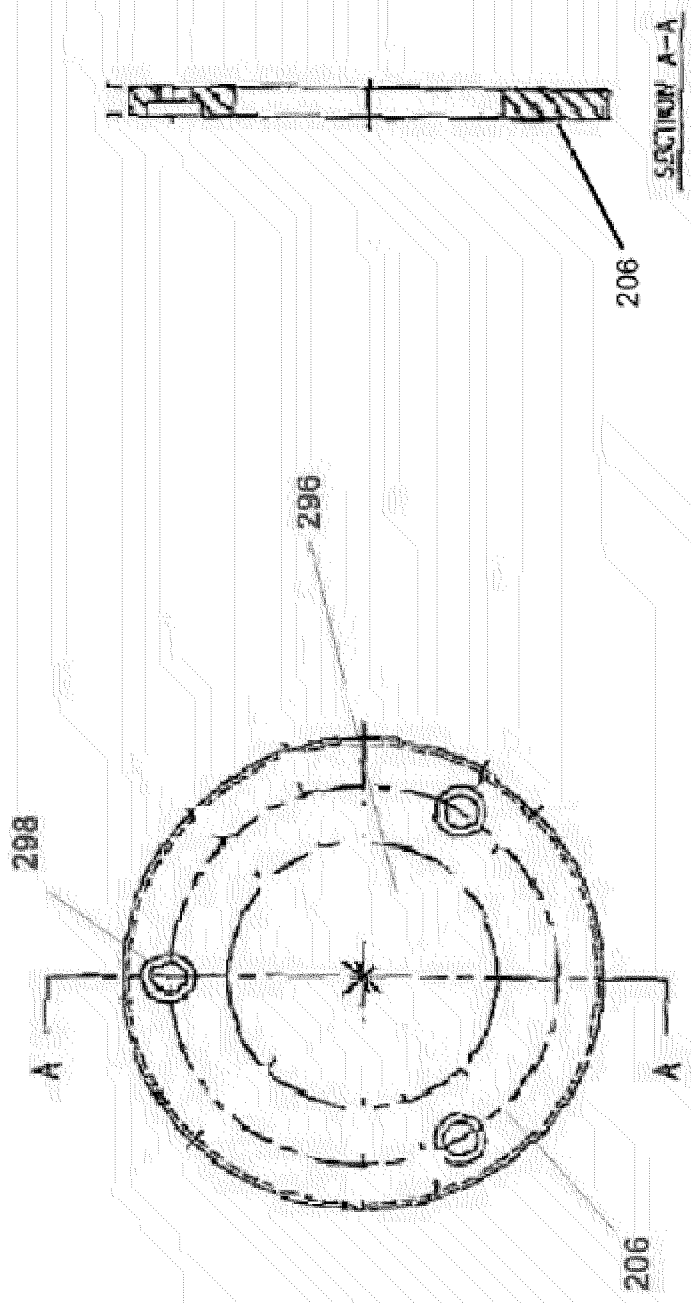


FIG. 12A

FIG. 12B

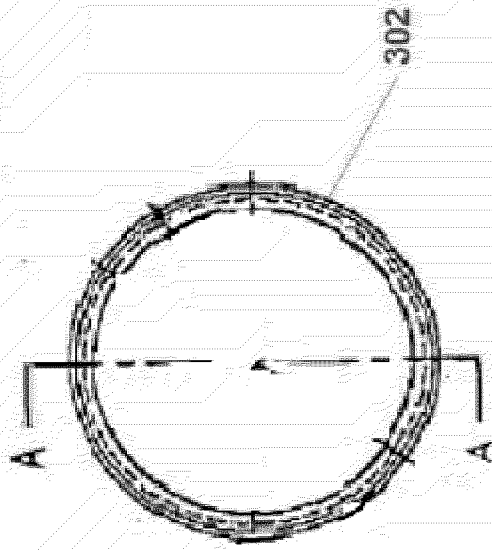
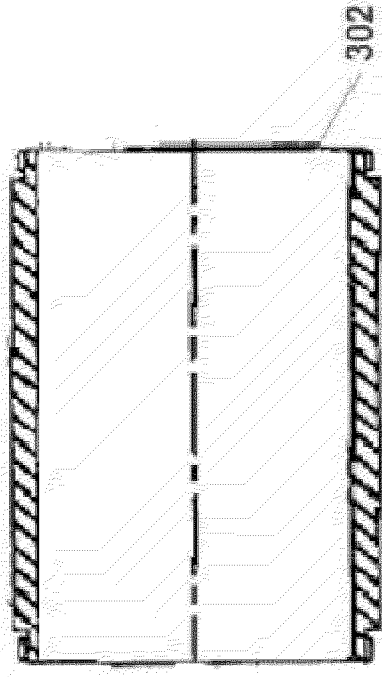


FIG. 13A



SECTION A-A

FIG. 13B

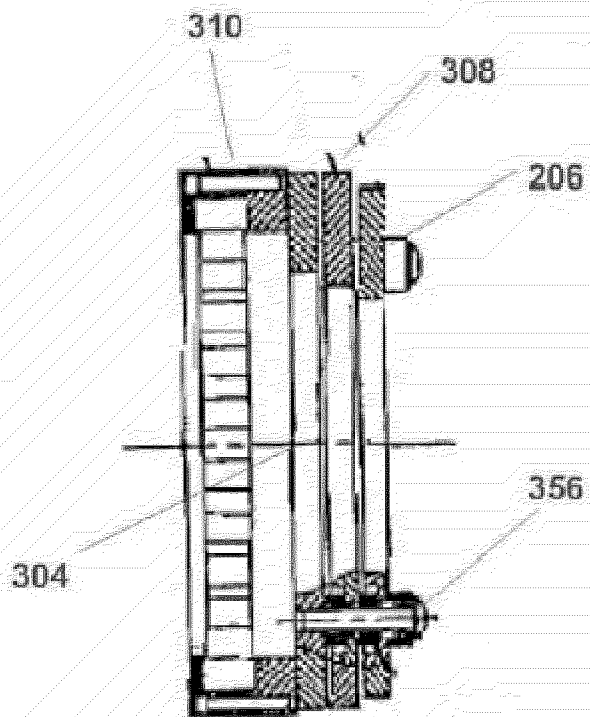


FIG. 14

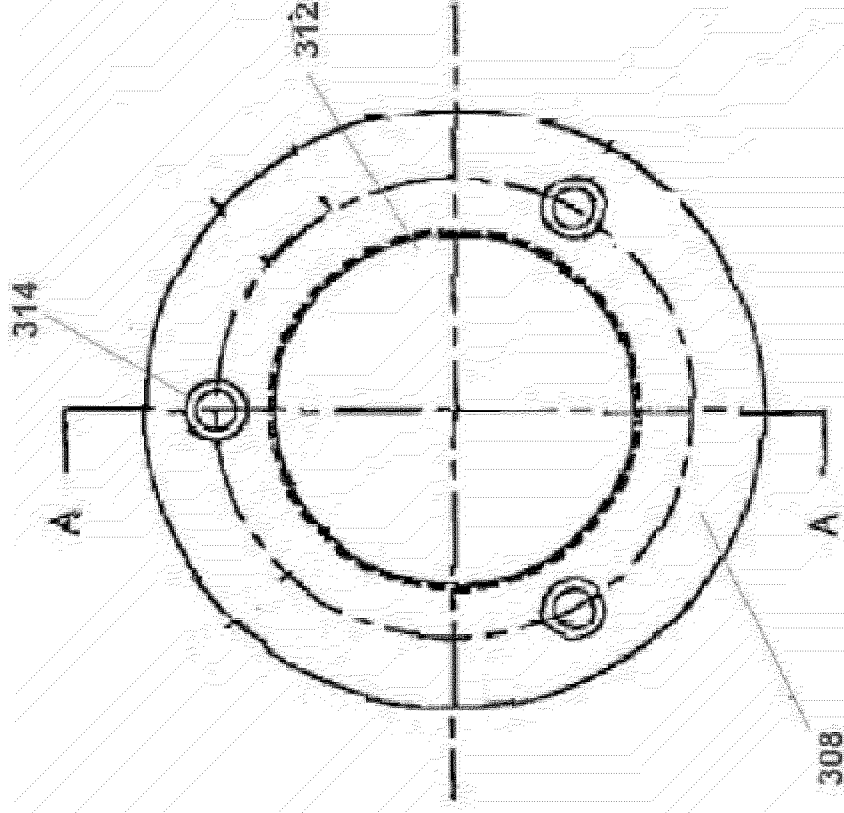


FIG. 15A

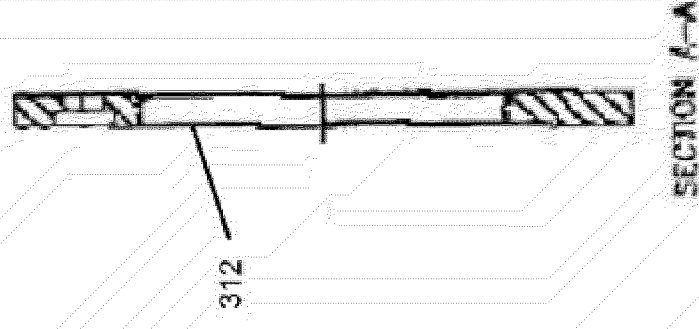


FIG. 15B

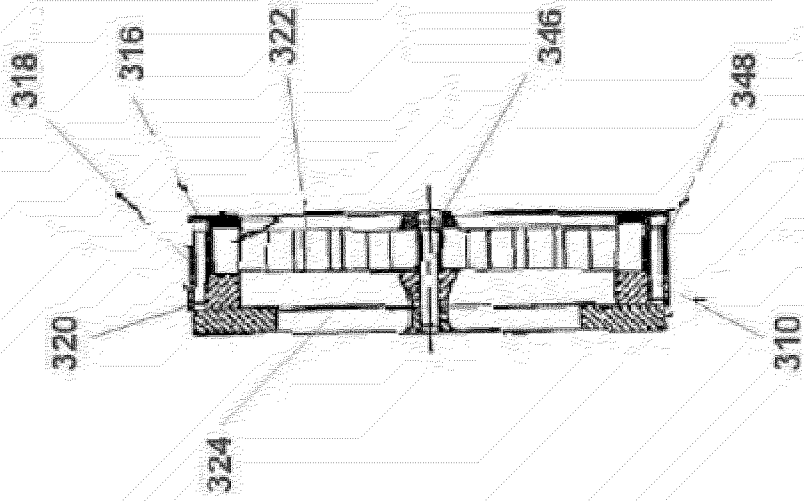


FIG 16A

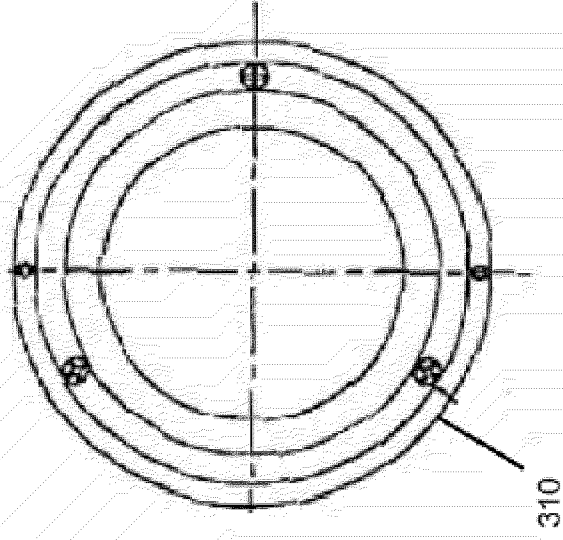
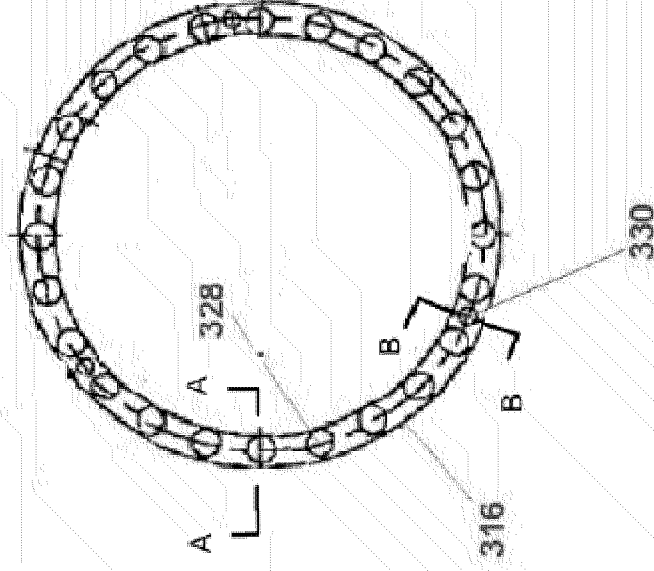


FIG. 16B



SECTION A-A

FIG. 17B



SECTION B-B

FIG. 17C

FIG. 17A

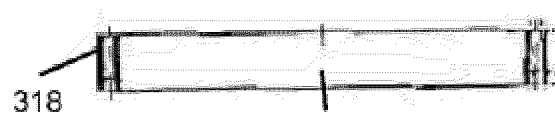
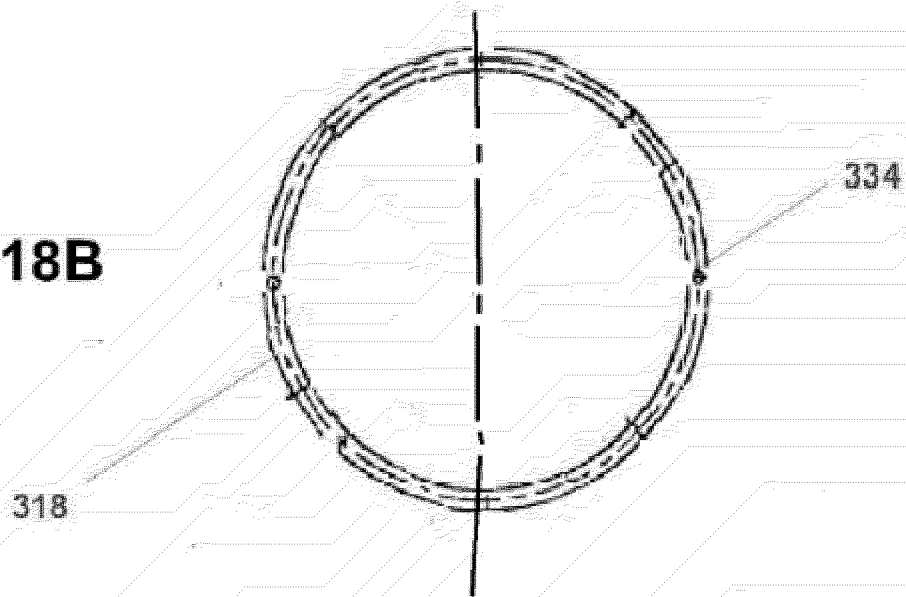


FIG. 18A

FIG. 18B



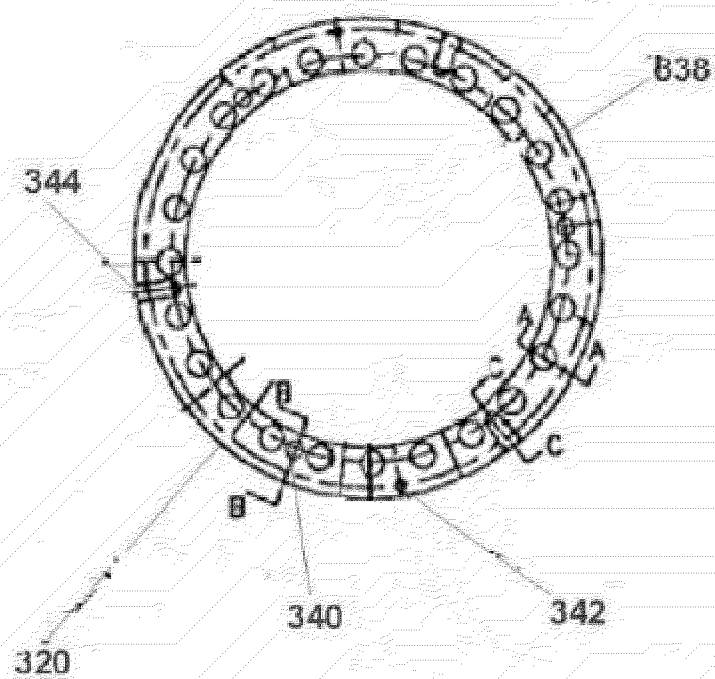
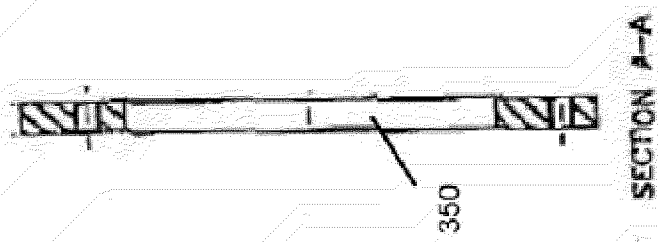
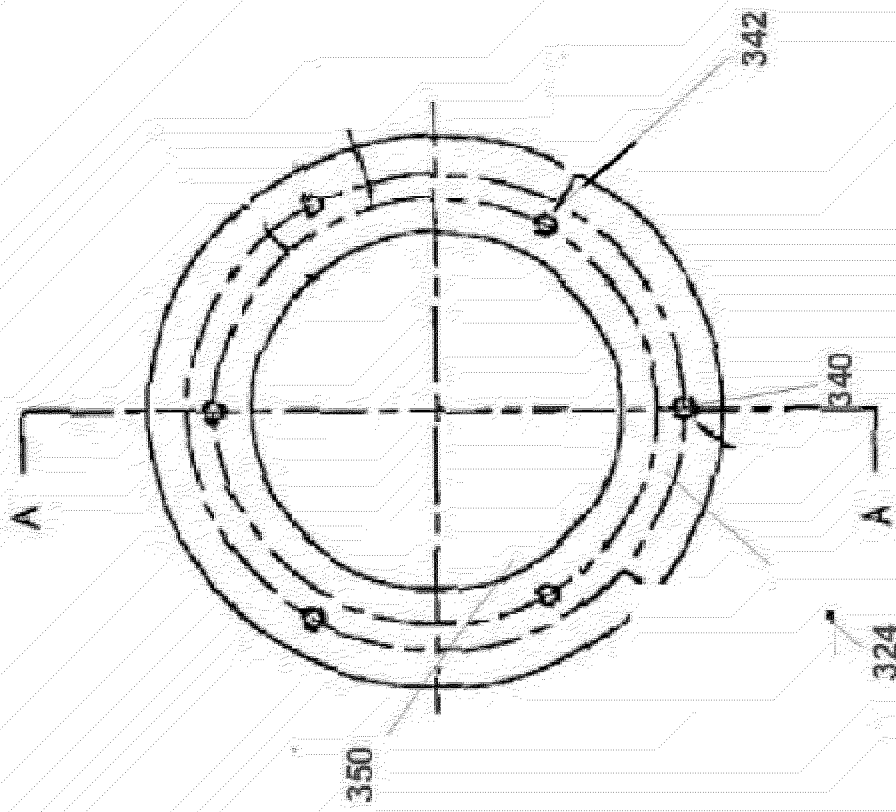


FIG. 19



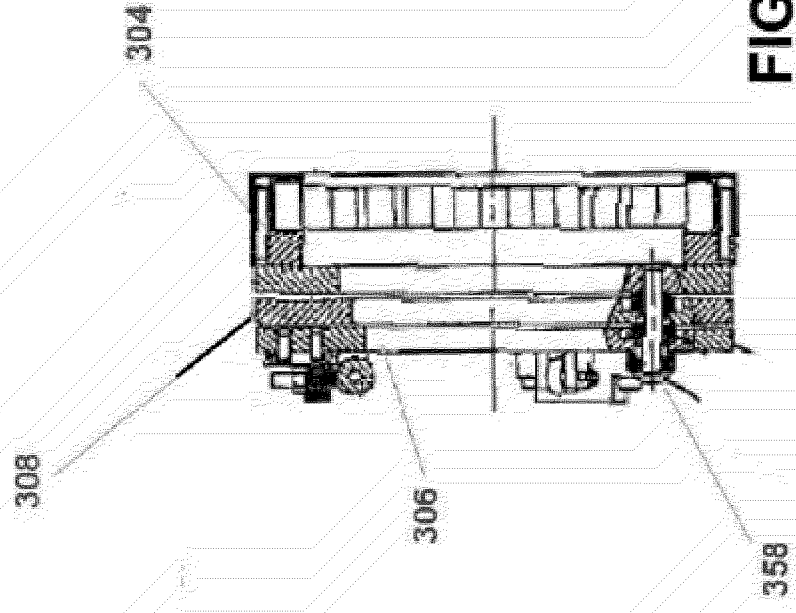


FIG. 21B

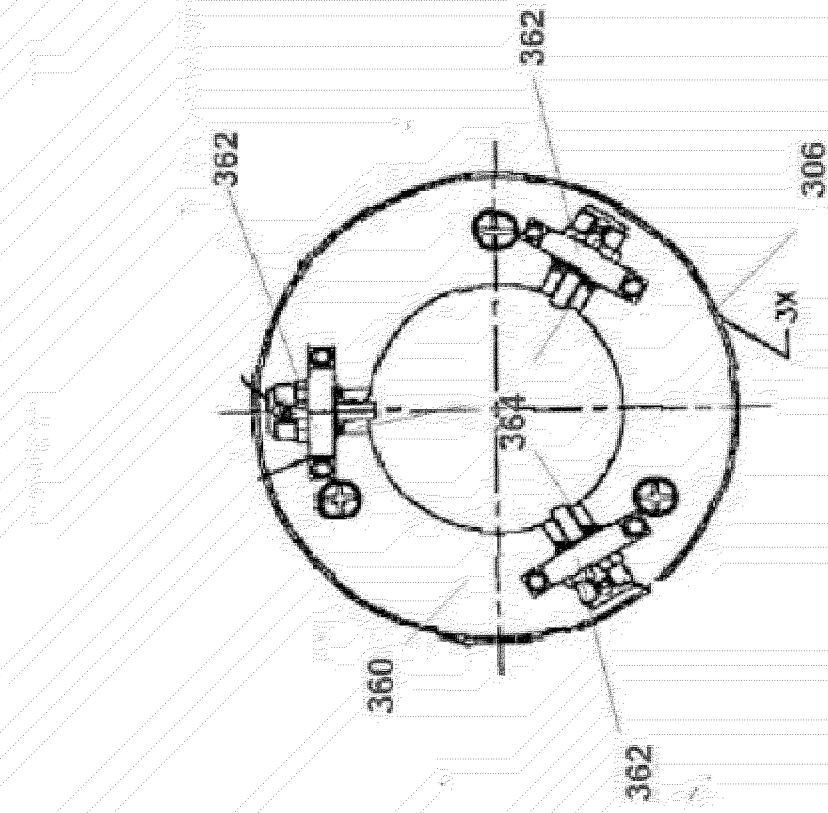
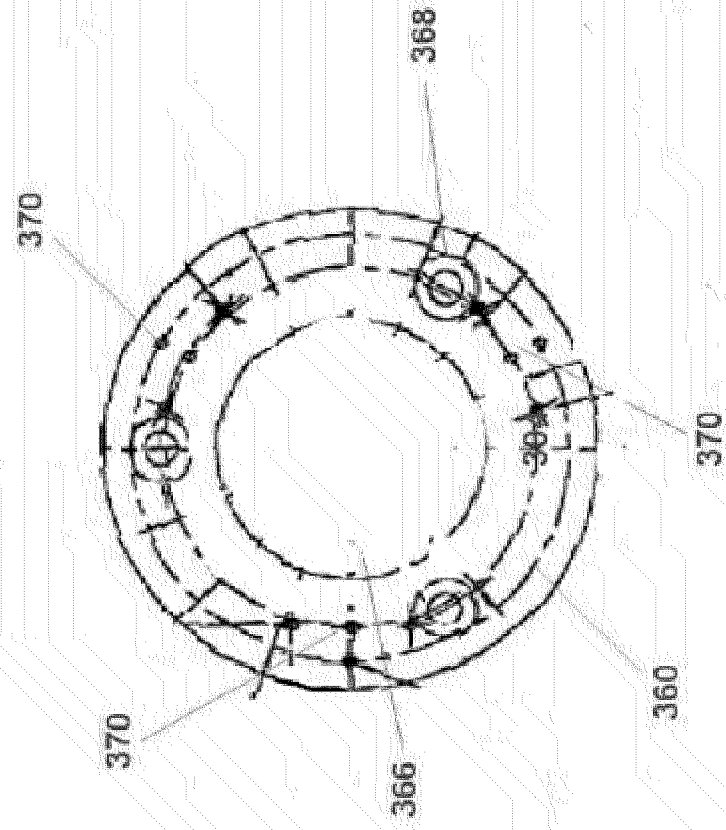


FIG. 21A



SECTION A-A

FIG. 22B

FIG. 22A

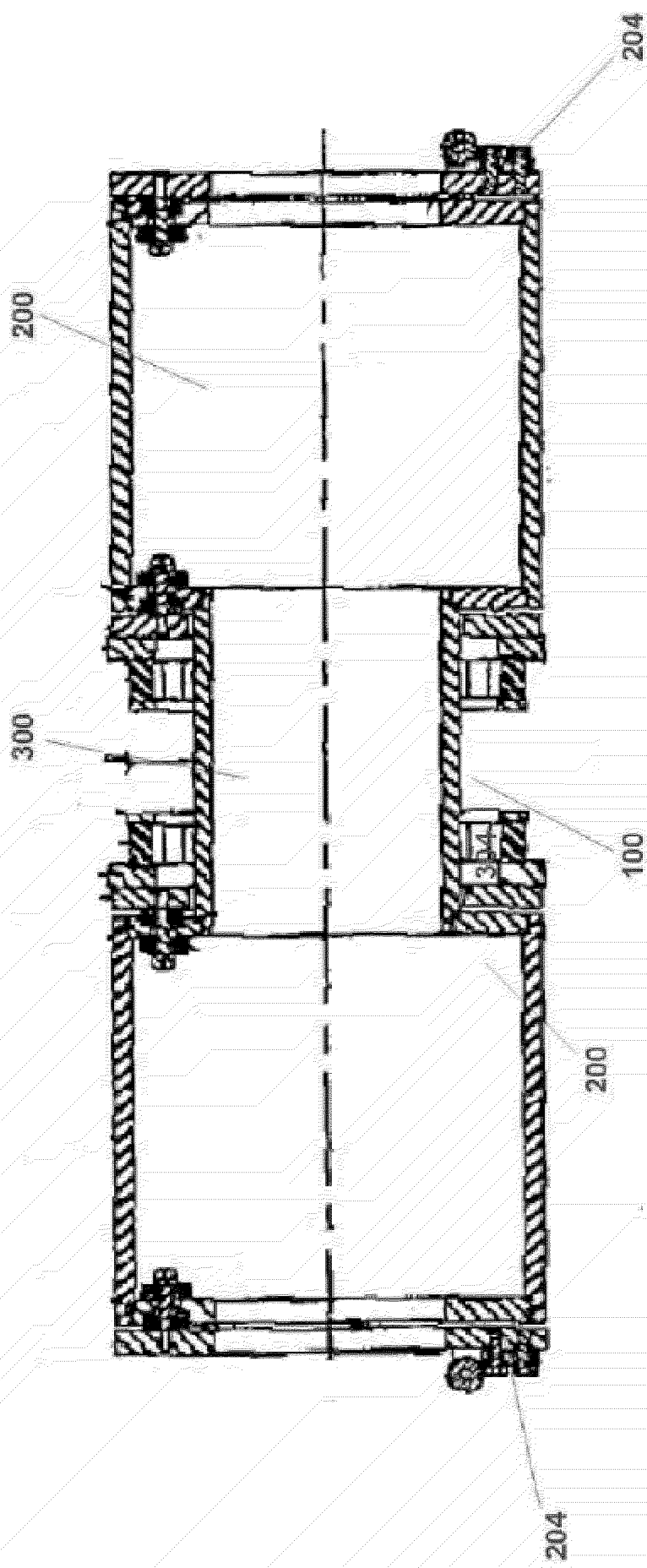


FIG. 23

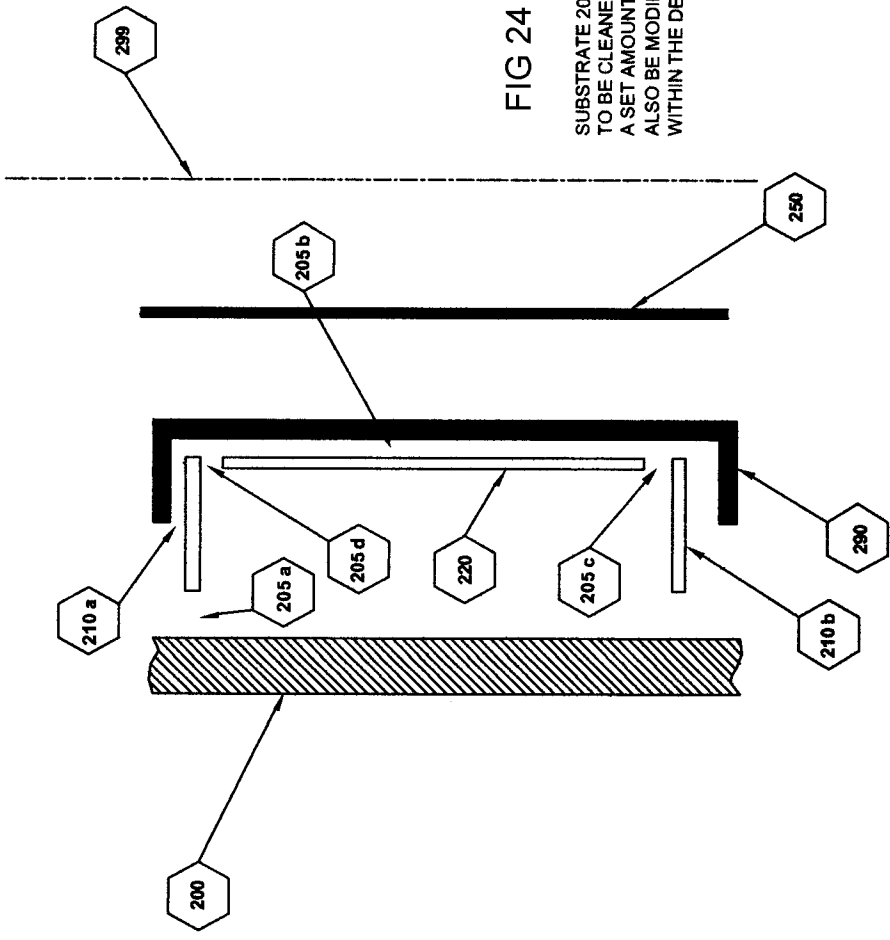


FIG 24

SUBSTRATE 200 AND TARGET 250 ARE SURFACES TO BE CLEANED OF RESIDUAL CONTAMINATION OR A SET AMOUNT OF MATERIAL DEPTH. SURFACES CAN ALSO BE MODIFIED BY A PROCESS THAT IS CONTAINED WITHIN THE DEVICE.

FIG 24

FIG 25

IS A CROSS SECTIONAL
VIEW OF THE PLASMA CLEANING
AND COLLECTION DEVICE
COMPRISING OF AN INTERNALLY
GENERATED MAGNETIC FIELD.

THE COLLECTION SURFACE IS
NUMBERED: 320, 310 a, AND 320 b.

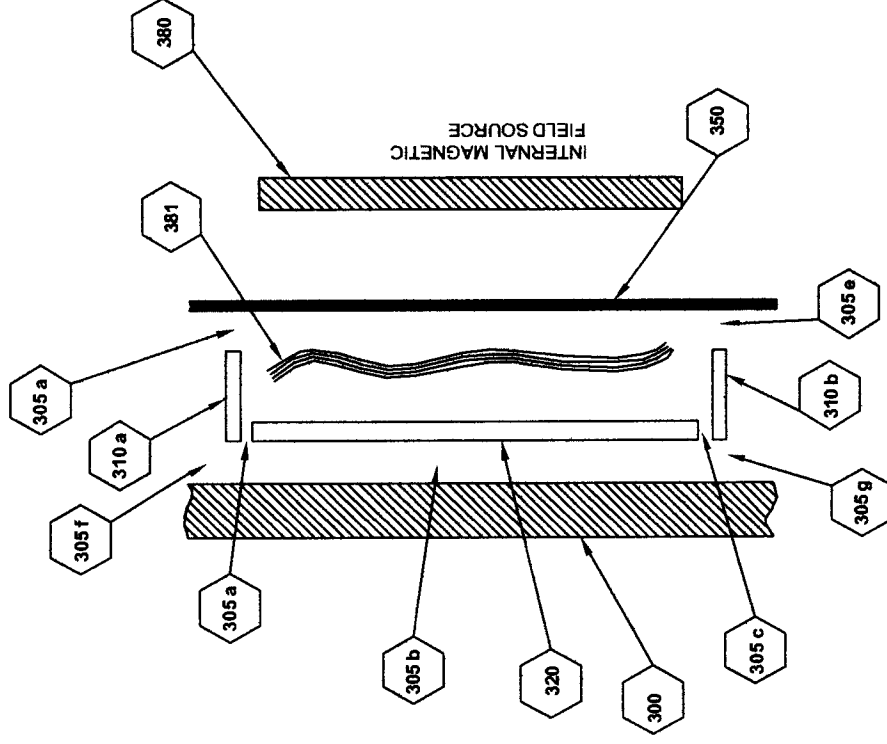


FIG 25

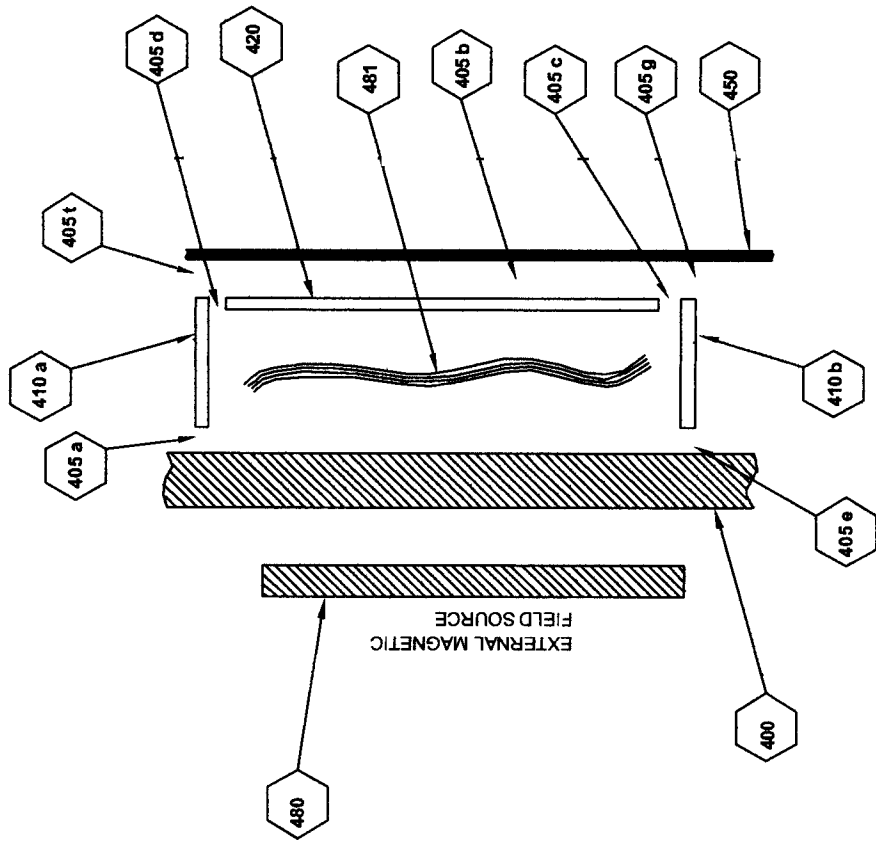
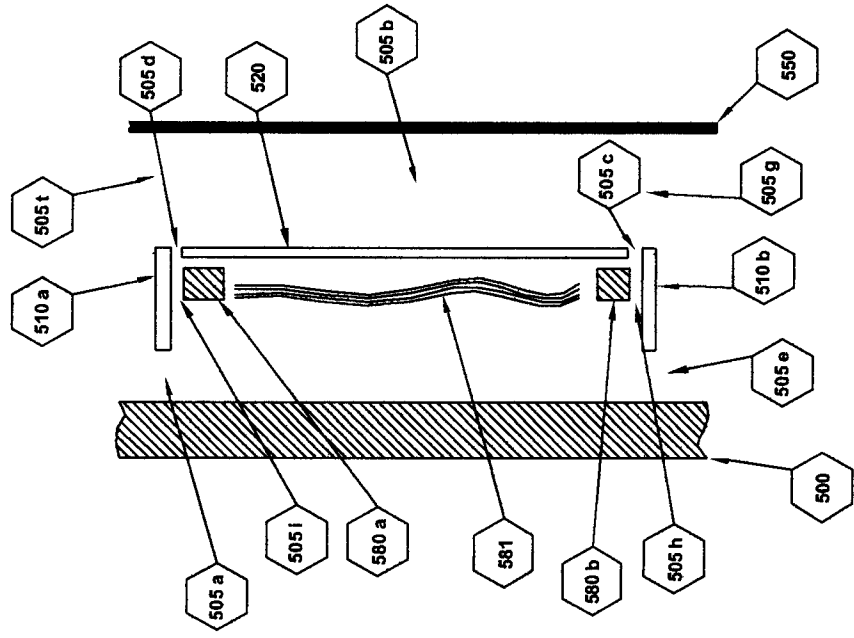


FIG 26



MAGNETIC FIELD SOURCE ON DEVICE
LOCATED WITHIN HOUSING

FIG 27